74LVC11

Triple 3-input AND gate Rev. 6 — 17 November 2011

Product data sheet

1. **General description**

The 74LVC11 provides three 3-input AND functions.

Features and benefits 2.

- Wide supply voltage range from 1.2 V to 3.6 V
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - HBM JESD22-A114F exceeds 2000 V
 - ♦ MM JESD22-A115-B exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

Ordering information 3.

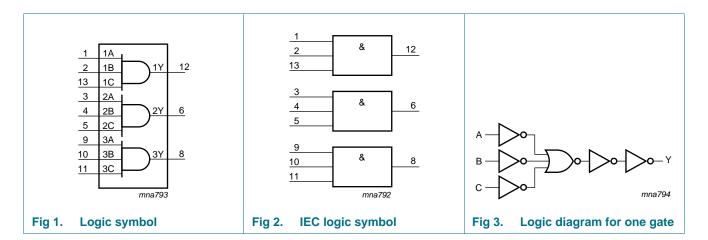
Table 1. **Ordering information**

Type number	Package	Package									
	Temperature range	Name	Description	Version							
74LVC11D	–40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1							
74LVC11DB	–40 °C to +125 °C	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1							
74LVC11PW	–40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1							
74LVC11BQ	–40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 \times 3 \times 0.85 mm	SOT762-1							



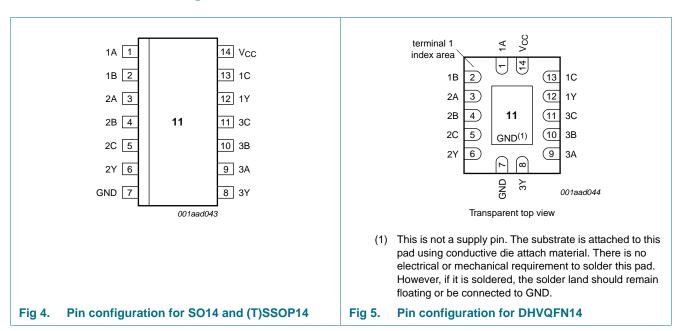
Triple 3-input AND gate

4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A	1, 3, 9	data input
1B, 2B, 3B	2, 4, 10	data input
1C, 2C, 3C	13, 5, 11	data input

74LVC11

Triple 3-input AND gate

Table 2. Pin description ... continued

Symbol	Pin	Description
1Y, 2Y, 3Y	12, 6, 8	data output
GND	7	ground (0 V)
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function selection[1]

Input	nput					
nA	nB	nC	nY			
L	X	X	L			
X	L	X	L			
X	X	L	L			
Н	Н	Н	Н			

^[1] H = HIGH voltage level; L = LOW voltage level; X = don't care

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
VI	input voltage		[<u>1]</u> -0.5	+6.5	V
I _{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0 V$	-	±50	mA
Vo	output voltage		<u>[2]</u> -0.5	$V_{CC} + 0.5$	V
Io	output current	$V_O = 0 V to V_{CC}$	-	±50	mA
I _{CC}	supply current		-	100	mA
I_{GND}	ground current		-100	-	mA
P _{tot}	total power dissipation	$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$	<u>[3]</u> _	500	mW
T _{stg}	storage temperature		-65	+150	°C

^[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

^[2] The output voltage ratings may be exceeded if the output current ratings are observed.

^[3] For SO14 packages: above 70 °C the value of P_D derates linearly with 8 mW/K.
For (T)SSOP14 packages: above 60 °C the value of P_D derates linearly with 5.5 mW/K.
For DHVQFN14 packages: above 60 °C the value of P_D derates linearly with 4.5 mW/K.

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Triple 3-input AND gate

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
VI	input voltage		0	-	5.5	V
Vo	output voltage		0	-	V_{CC}	V
T _{amb}	ambient temperature		-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	$V_{CC} = 1.65 \text{ V to } 2.7 \text{ V}$	0	-	20	ns/V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40	°C to +8	35 °C	-40 °C to	+125 °C	Unit
			Min	Typ[1]	Max	Min	Max	
V _{IH}	HIGH-level	V _{CC} = 1.2 V	1.08	-	-	1.08	-	V
	input voltage	V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V_{IL}	LOW-level	V _{CC} = 1.2 V	-	-	0.12	-	0.12	V
	input voltage	V _{CC} = 1.65 V to 1.95 V	-	-	$0.35 \times V_{CC}$	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V _{OH} HIGH-level output voltage	HIGH-level	$V_I = V_{IH}$ or V_{IL}						
	-	$I_O = -100 \mu A;$ $V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	V _{CC} - 0.2	-	-	V _{CC} – 0.3	-	V
		$I_{O} = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	-	-	1.05	-	V
		$I_{O} = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.8	-	-	1.65	-	V
		$I_{O} = -12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	2.2	-	-	2.05	-	V
		$I_{O} = -18 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.4	-	-	2.25	-	V
		$I_{O} = -24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.2	-	-	2.0	-	V
V_{OL}	LOW-level	$V_I = V_{IH}$ or V_{IL}						
	output voltage	$I_O = 100 \mu A;$ $V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	-	-	0.2	-	0.3	V
		$I_O = 4 \text{ mA}$; $V_{CC} = 1.65 \text{ V}$	-	-	0.45	-	0.65	V
		$I_O = 8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.6	-	0.8	V
		$I_O = 12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	-	-	0.4	-	0.6	V
		$I_O = 24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.55	-	0.8	V
I _I	input leakage current	V_{CC} = 3.6 V; V_I = 5.5 V or GND	-	±0.1	±5	-	±20	μΑ

Triple 3-input AND gate

Table 6. Static characteristics ... continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40	°C to +85	5 °C	–40 °C to	Unit	
			Min	Typ[1]	Max	Min	Max	
I _{CC}	supply current	$V_{CC} = 3.6 \text{ V}; V_I = V_{CC} \text{ or GND};$ $I_O = 0 \text{ A}$	-	0.1	10	-	40	μΑ
ΔI_{CC}	additional supply current	per input pin; $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V};$ $V_I = V_{CC} - 0.6 \text{ V};$ $I_O = 0 \text{ A}$	-	5	500	-	5000	μА
C _I	input capacitance	$V_{CC} = 0 \text{ V to } 3.6 \text{ V};$ $V_{I} = \text{GND to } V_{CC}$	-	5.0	-	-	-	pF

^[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 7.

Symbol	Parameter	Conditions		-40	°C to +8	5 °C	–40 °C to	+125 °C	Unit
				Min	Typ[1]	Max	Min	Max	
t_{pd}	propagation delay	nA, nB, nC to nY; see Figure 6	[2]						
		$V_{CC} = 1.2 \text{ V}$		-	14.0	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V		1.0	4.7	12.2	1.0	14.1	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		1.5	2.8	6.9	1.5	8.0	ns
		$V_{CC} = 2.7 \text{ V}$		1.5	2.9	7.0	1.5	8.1	ns
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$		1.5	2.5	6.2	1.5	7.2	ns
C_{PD}	power dissipation	per gate; $V_I = GND$ to V_{CC}	[3]						
	capacitance	V_{CC} = 1.65 V to 1.95 V		-	3.1	-	-	-	pF
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-	6.2	-	-	-	pF
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$		-	9.0	-	-	-	pF

^[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where:

 f_i = input frequency in MHz; f_o = output frequency in MHz

 C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

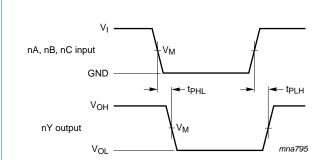
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs

^[2] t_{pd} is the same as t_{PLH} and t_{PHL} .

^[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

Triple 3-input AND gate

11. AC waveforms

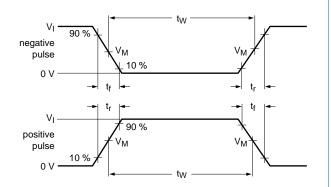


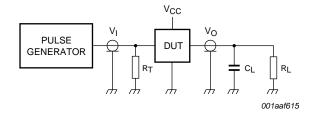
 V_M = 1.5 V at $V_{CC} \ge 2.7$ V

 V_{M} = 0.5 \times V_{CC} at V_{CC} < 2.7 V.

 $\ensuremath{V_{OL}}$ and $\ensuremath{V_{OH}}$ are typical output voltage levels that occur with the output load.

Fig 6. Input (nA, nB and nC) to output (nY) propagation delays





Test data is given in $\underline{\text{Table 8}}$. Definitions for test circuit:

 R_L = Load resistance.

 C_L = Load capacitance including jig and probe capacitance.

 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 7. Load circuitry for measuring switching times

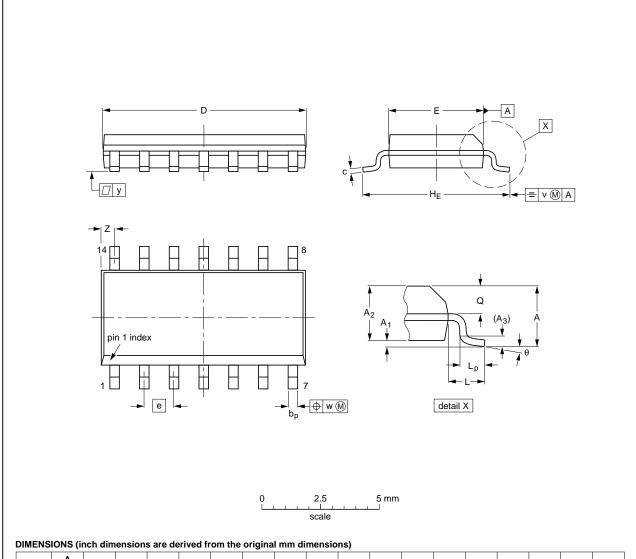
Table 8. Test data

Supply voltage	Input		Load	Load		
	VI	t _r , t _f	C _L	R _L		
1.2 V	V _{CC}	≤ 2 ns	30 pF	1 kΩ		
1.65 V to 1.95 V	V _{CC}	≤ 2 ns	30 pF	1 kΩ		
2.3 V to 2.7 V	V _{CC}	≤ 2 ns	30 pF	500 Ω		
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω		
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω		

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01	l	0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE						ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT108-1	076E06	MS-012				99-12-27 03-02-19

Fig 8. Package outline SOT108-1 (SO14)

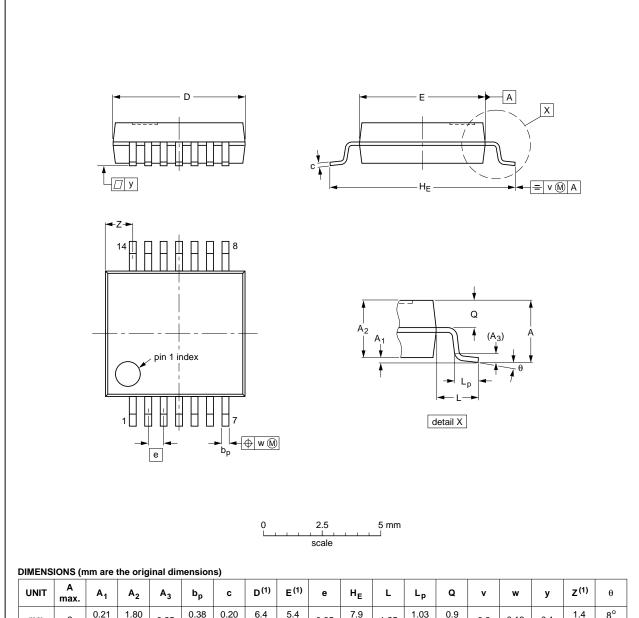
74LVC11

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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



UNIT	A max.	A ₁	A ₂	A ₃	b _p	С	D ⁽¹⁾	E ⁽¹⁾	e	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE				
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE		
SOT337-1		MO-150				-99-12-27 03-02-19		
						03-02-19		

Fig 9. Package outline SOT337-1 (SSOP14)

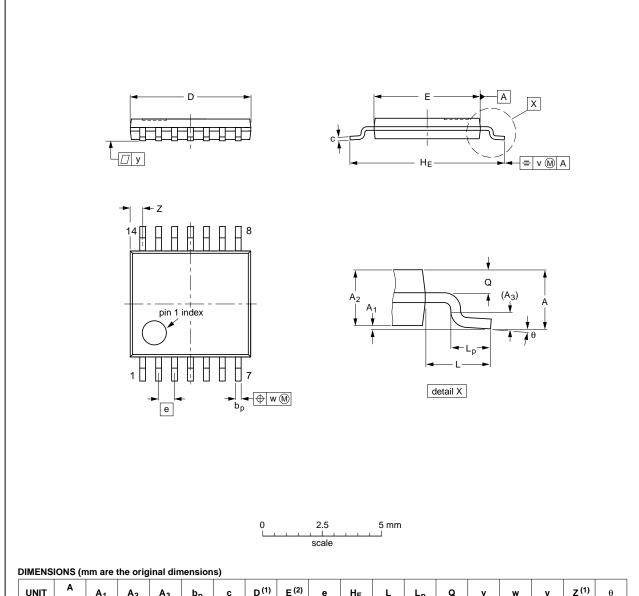
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TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



-							~,												
	UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E (2)	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
	mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE		
SOT402-1		MO-153			99-12-27 03-02-18		
				·			

Fig 10. Package outline SOT402-1 (TSSOP14)

74LVC1

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DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm SOT762-1

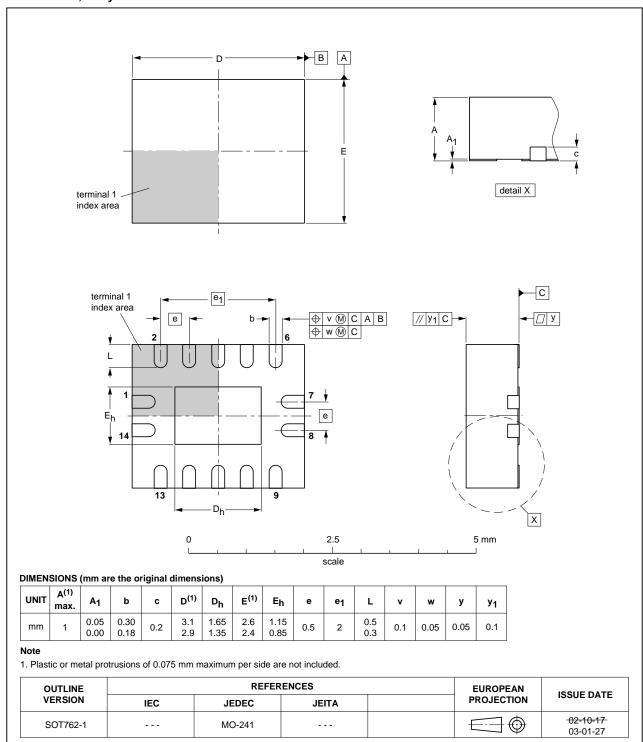


Fig 11. Package outline SOT762-1 (DHVQFN14)

Triple 3-input AND gate

13. Abbreviations

Table 9. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
НВМ	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC11 v.6	20111117	Product data sheet	-	74LVC11 v.5
Modifications:	 Legal pages u 	pdated.		
	 <u>Table 6</u>, bodyr 	ow ΔI_{CC} : condition V_{CC} chan	ged.	
74LVC11 v.5	20111025	Product data sheet	-	74LVC11 v.4
74LVC11 v.4	20040113	Product specification	-	74LVC11 v.3
74LVC11 v.3	19980428	Product specification	-	74LVC11 v.2
74LVC11 v.2	19980428	Product specification	-	74LVC11 v.1
74LVC11 v.1	-	-	-	-

Triple 3-input AND gate

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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Triple 3-input AND gate

17. Contents

1	General description
2	Features and benefits
3	Ordering information 1
4	Functional diagram 2
5	Pinning information 2
5.1	Pinning
5.2	Pin description 2
6	Functional description 3
7	Limiting values 3
8	Recommended operating conditions 4
9	Static characteristics 4
10	Dynamic characteristics 5
11	AC waveforms 6
12	Package outline 7
13	Abbreviations11
14	Revision history 11
15	Legal information 12
15.1	Data sheet status
15.2	Definitions
15.3	Disclaimers
15.4	Trademarks13
16	Contact information 13
17	Contents

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AMEYA360 Components Supply Platform

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